

PRODUCT DATA SHEET

K-291 2 MIL POLYESTER FILM TAPE

APPLICATIONS

Designed for very high temperature masking applications. Ideal for use in powder coat applications and for masking printed circuit boards during various production processes. Also suitable for splicing applications. Temperature ranges from -100° to 350° F (-73° to 177°C).

FEATURES/BENEFITS

- The high performance silicone adhesive system features excellent adhesion to printed circuit boards during the wave soldering process with clean one piece removal.
- The high temperature polyester film absorbs heat without shrinking or losing its construction integrity.
- K-291 utilizes a 2 mil polyester film, with excellent puncture, tear and abrasion resistance at elevated temperatures.
- Also available in die-cut form for spot masking.

TECHNICAL DATA

Backing material

: 2 mil Polyester Film

Adhesive

: Silicone

Color

: Emerald Green

Tape thickness

: 3.5 mils/0.089 mm

Elongation

: 100%

Adhesion to steel
Tensile strength

30 oz per inch/850 g/25mm50 lbs per inch/23 kg/25mm

Standard length

: 72 yards

Note: The above are typical values obtained from tests recommended by the PSTC, ASTM, or government agencies and should not be used in writing specifications.